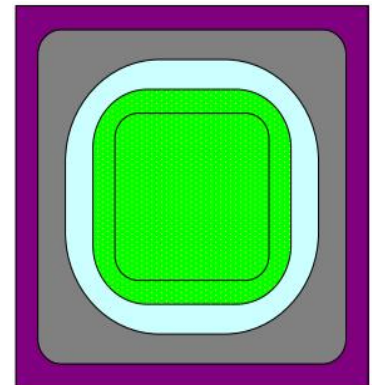
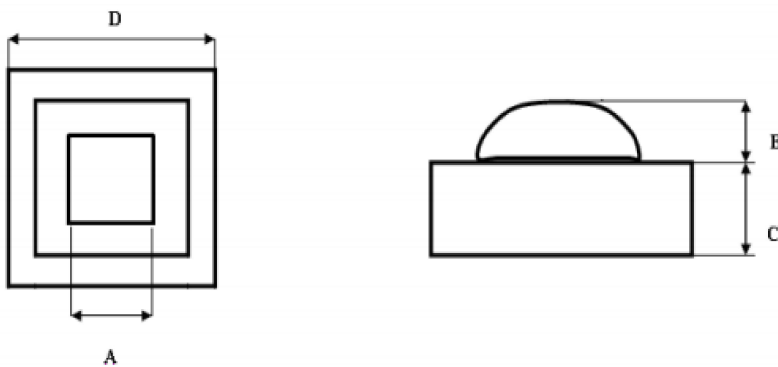


Features

- Epitaxial Zener Chip
- Suitable for glass-tube package.
- Plating metal: Back side:Ag, Top side: Ag ball
- Die size: 0.40mm*0.40mm
- Die thickness: 140mil
- Wafer size: 5", PDPW: 68,000die/wafer



Chip outline



Parameter	Symbol	Min. Value	Typical Value	Max. Value	Unit
Chip size	D	360		380	uM
chip thickness	C	120		160	uM
Silver ball size	A	245		300	uM
Silver ball height	B	30		60	uM
Street size	/		40		uM

MAXIMUM RATINGS

Parameter	Symbol	Test Condition	Value	Unit
Power dissipation	P_D	$T_a=25^{\circ}C$, Lead length=8mm	1	W
Operating temperature	T_J		175	$^{\circ}C$
Storage temperature	T_{STG}		-50~+175	$^{\circ}C$

Electrical Characteristics ((Rating at 25°C ambient, refer to the Finished Goods)
($V_F < 1.16V @ I_F = 200mA$)

Part No.	$V_Z @ I_Z = 12.5mA$		Zener impedance				Max.Reverse leakage current @ V_R	
	Min.	Max.	$Z_{ZK}(\Omega) @ I_{ZK}$	$I_{ZK}(mA)$	$Z_{ZK}(\Omega) @ I_{ZK}$	$I_{ZK}(mA)$	$I_R(\mu A)$	$V_R(V)$
GDZ2CW040200YQS	19.05	20.95	750	0.25	22	12.5	0.5	15.2